TOSHIBA Bipolar Linear IC Silicon Monolithic

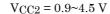
TA2131FN

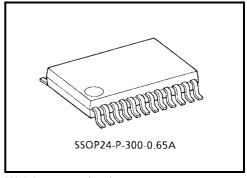
Low Current Consumption Headphone Amplifier for Portable MD Player (With Bass Boost Function)

The TA2131FN is a low current consumption headphone amplifier developed for portable digital audio. It is particularly well suited to portable MD players that are driven by a single dry cell. It also features a built-in bass boost function with AGC, and is capable of bass amplification of DAC output and analog signals such as tuner.

Features

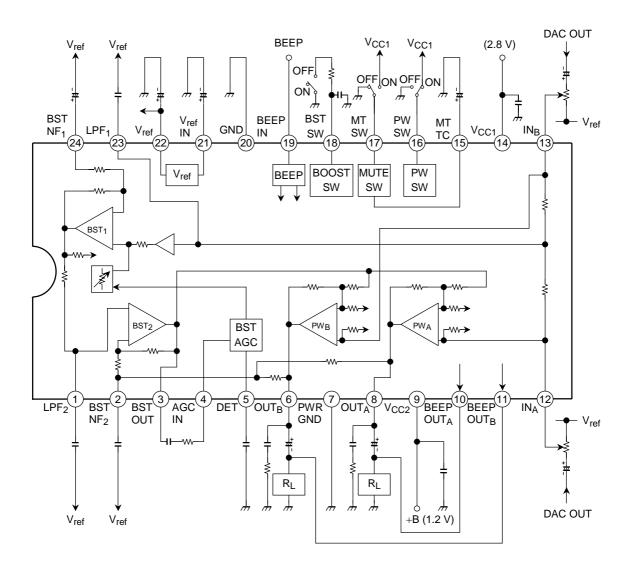
- Low current consumption: ICCQ (VCC1) = 0.55 mA (typ.) ICCQ (VCC2) = 0.20 mA (typ.)
- Output power: $P_0 = 8$ mW (typ.) ($V_{CC1} = 2.8$ V, $V_{CC2} = 1.2$ V, f = 1 kHz, THD = 10%, $R_L = 16$ Ω)
- Low noise: $V_{no} = -102 dBV$ (typ.)
- Built-in low-pass boost (with AGC)
- I/O pin for beep sound
- Outstanding ripple rejection ratio
- Built-in power mute
- Built-in power ON/OFF switch
- Operating supply voltage range (Ta = 25°C): $V_{CC1} = 1.8 \sim 4.5 \text{ V}$





Weight: 0.14 g (typ.)

Block Diagram



Terminal Explanation (Terminal voltage: Typical terminal voltage at no signal with test circuit, $V_{CC1} = 2.8 \text{ V}$, $V_{CC2} = 1.2 \text{ V}$, $Ta = 25 ^{\circ}\text{C}$)

Te	erminal No.	Terminal Explanation	Internal Circuit		
1	LPF ₂	BST amplifier 1 output (filter terminal)	PWA ADD AGC BST ₂ S BST ₂ NAMP	0.61	
23	LPF ₁	ADD amplifier output (filter terminal)	10 kΩ 12 kΩ 12 kΩ 13 PW _B 30 kΩ	0.61	
24	BST NF ₁	BST amplifier 1 NF	Z4 1 1 Vref	0.61	
2	BST NF ₂	BST amplifier 2 NF terminal (low-pass compensation condenser connection terminal)	GA PWA	0.61	
3	BST OUT	BST amplifier 2 output terminal	20 KD		
6	OUTB	Power amplifier	BST1 $10 \text{ k}\Omega$ $15 \text{ k}\Omega$ OUT C C $BST2$ C	0.61	
8	OUT _A	output	C 2 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0		
12	IN _A	Power amplifier		0.61	
13	IN _B	input	PW _B	0.01	

Te	erminal No.	Terminal Explanation	Internal Circuit			
4	AGC IN	Signal input level to BST amplifier is varied according to the input level to the boost AGC input terminal. Input impedance: $15~\mathrm{k}\Omega$ (typ.)	Vref 4 w 10 kΩ			
5	DET	Smoothing of boost AGC level detection	(a) (b) (c) (c) (c) (c) (c) (c) (c) (c) (c) (c			
7	PWR GND	GND of power amplifier output stage	_	0		
9	V _{CC2}	V _{CC} (+B) at power amplifier output stage	_	1.2		
10	BEEP OUT _A	Beep sound output	14	_		
11	BEEP OUT _B	terminal	19 10 kΩ 19 10 m			
19	BEEP IN	Beep sound input terminal Receives beep sound signals from microcomputer.				
14	V _{CC1}	Main V _{CC}	_	2.8		
15	МТ ТС	Mute smoothing Power mute switch Reduces the shock noise during switching	14 W C J J J J J J J J J J J J J J J J J J			

Te	Terminal No. Terminal Explanation		Internal Circuit	Terminal Voltage (V)
16	PW SW	Power ON/OFF switch "H" level: IC operation "L" level: IC OFF Refer to function explanation 5	V _{CC1} 14 16 47 kΩ	
17	MT SW	Mute switch "L" level: mute reset "H" level: mute ON Refer to function explanation 5	V _{CC1} 147 kΩ 17 - W 17 - W 18 - M 18 -	
18	BST SW	Bass boost ON/OFF switch "H" level/OPEN: BST ON "L" level: BST OFF Refer to function explanation 5	14 18 20 kΩ 18	
20	GND	GND of input stage in power amplifier	_	0
21	V _{ref} IN	Reference voltage circuit filter terminal	14 \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\	0.61
22	V _{ref}	Reference voltage circuit	21 10 kΩ 22 π/π π/π	0.61

Function Explanation

1. Bass Boost Function

1-1 Description of Operation

TA2131FN has a bass boost function for bass sound reproduction built-in to the power amplifier. With the bass boost function, at medium levels and lower, channel A and channel B are added for the low frequency component, and output to BST amplifier 2 (BST₂) in negative phase. That signal is inverted and added before being subjected to bass boost. If the signal of the low-frequency component reaches a high level, the boost gain is controlled to main a low distortion (see Fig.1).

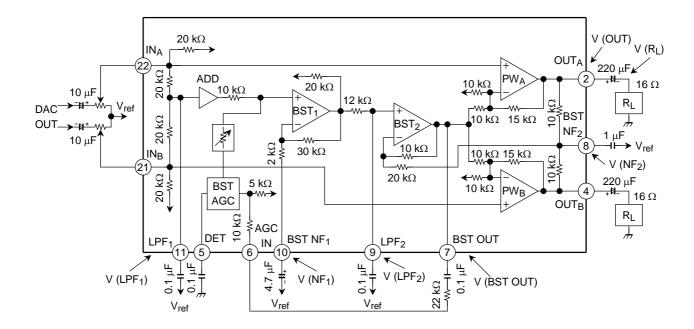


Figure 1 System Diagram of Bass Boost

1-2 AGC Circuit

The AGC circuit of the bass boost function detects with "AGC DET" the voltage component created by "BST₂," and as the input level increases, the variable impedance circuit is changed, and the bass boost signal is controlled so that it is not assigned to BST amplifier 1. In this way, the bass signal to "BST₂" input is shut-off, and that boost gain is controlled.

1-3 Bass Boost System

As shown in Fig.1, the flow of the bass boost signal is that the signal received from power amplifier input goes through LPF1, ADD amplifier, ATT (variable impedance circuit), BPF1 (BST amplifier 1) and LPF2, and the negative phase signal to the power amplifier input signal is output from BST amplifier 2. The reason why it becomes the negative phase of the BST amplifier 2 signal is that the phase is inverted by 180° in the audible bandwidth by the secondary characteristics of LPF1 and LPF2 in Fig.1.

Ultimately the main signal and the bass boost signal formed before BST_2 are added. Fig.2 shows the frequency characteristics to each terminal.

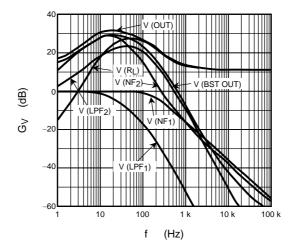


Figure 2 During Bass Boost (Frequency Characteristics to Each Terminal)

2. Low-Pass Compensation

2-1. Function

In C-couple type power amplifiers, it is necessary to give the output condenser C a large capacity to flatten out the frequency characteristics to the low frequency band (this is because the loss in the low frequency bandwidth becomes larger due to the effect of the high-pass filter comprising C and RL). Particularly when the headphone load is approximately $16~\Omega$ and an attempt is being made to achieve frequency characteristics of $\pm 3~dB$ at 20~Hz, a large capacity condenser of C = $470~\mu F$ is required. Bearing this situation in mind, a low-pass compensation function was built in to the TA2131FN, and while reducing the capacity of the output coupling condenser, almost flat ($\pm 3~dB$) frequency characteristics in all audible bandwidths (20~Hz to 20~kHz) have been achieved. Fig.3 shows the low-pass system diagram, and Fig.4 shows the frequency characteristics at each point. In Fig.4, (a) represents the status lost by the low-pass as a result of the high-pass filter comprising the headphone load ($RL = 16~\Omega$) and the output coupling condenser ($220~\mu F$) in the C-coupling system.

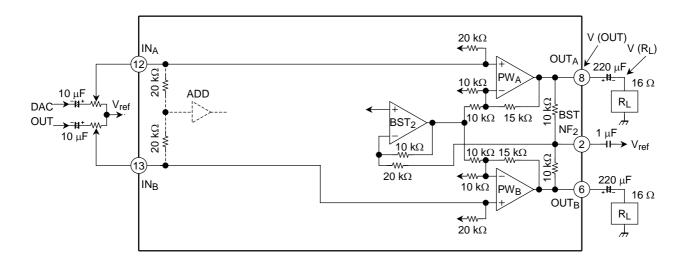


Figure 3 Low-Pass Compensation System Diagram

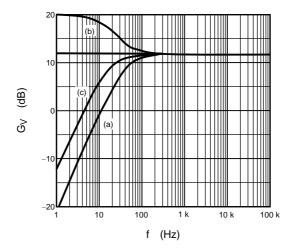


Figure 4 Power Amplifier Frequency Characteristics

<Principle of Low-Pass Compensation>

The low-pass component alone is extracted from the composite signal of PW_A/PW_B output, and that frequency signal is fed back to PW_A/PW_B once more via the inversion amplifier, thereby making it possible to increase the gain only of the low-pass component. The frequency characteristics of the power amplifier output V (OUT) in this state are shown in Fig.4 (b). In practice they are the frequency characteristics (c) viewed from load terminal V (R_L), and the low-pass is compensated relative to the state in (a).

2-2. Low-Pass Compensation Condenser and Crosstalk

In this low-pass compensation condenser circuit, processing is carried out using the composite signal of power amplifier output, so this affects crosstalk, according to the amount of compensation. f characteristics and crosstalk generated by the capacity of the condenser for compensation (2-pin) are shown below.

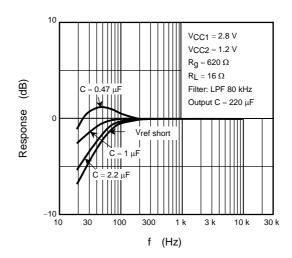


Figure 5 Condenser and f Characteristics for Low-Pass Compensation

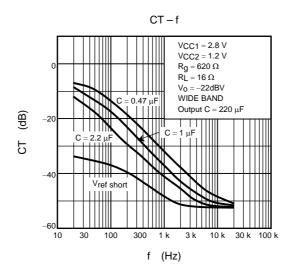
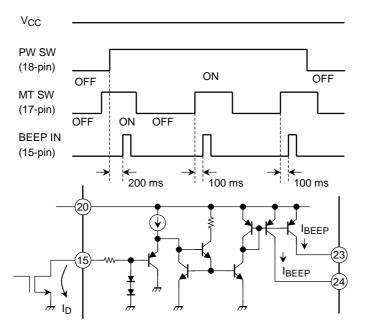


Figure 6 Low-Pass Compensation Condenser and Crosstalk

3. Beep

Beep sound signals from microcomputer can be received by the beep input terminal (19-pin). The PWA and PWB of the power amplifier during power mute are turned OFF, and the beep signal input from BEEP-IN (19-pin) is output from the BEEP-OUT terminal (10/11-pin) as fixed current, after passing through the converter and current amplification stage. Connecting this terminal to the headphone load outputs the beep sound.

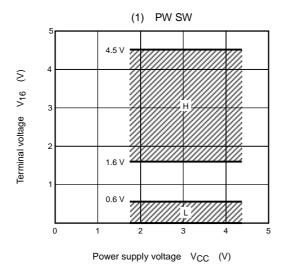
If the beep sound is not input, fix the BEEP-IN (19-pin) terminal to GND level.

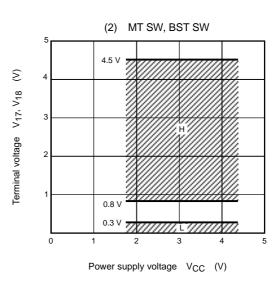


4. Power Switch

As long as the power switch is not connected to "H" level, the IC does not operate. If it malfunctions due to external noise, however, it is recommended to connect a pull-down resistor externally (the power switch is set to be highly sensitive).

5. Threshold Voltages of Switches





	PW SW (V ₁₆)		
"H" level	IC operation		
"L" level	IC OFF		

	MT SW (V ₁₇)
"H" level	Mute ON
"L" level	Mute reset

	BST SW (V ₁₈)
"H" level/OPEN	BST ON
"L" level	BST OFF

6. These capacitors which prevent oscillation of the power amplifier, and are between the V_{ref} and V_{CC} -GND must have a small temperature coefficient and outstanding frequency characteristics.

Maximum Ratings

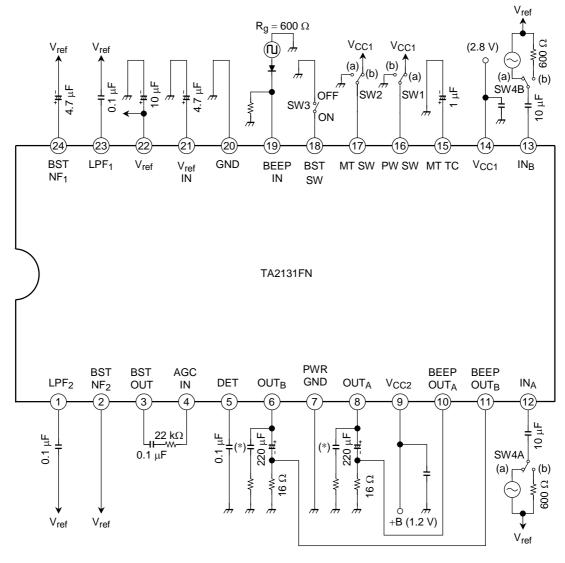
Characteristic	Symbol	Rating	Unit
Supply voltage	V _{CC}	4.5	V
Output current	I _{o (peak)}	100	mA
Power dissipation	P _D (Note)	500	mW
Operating temperature	T _{opr}	-25~75	°C
Storage temperature	T _{stg}	-55~150	°C

Note: Derated above $Ta = 25^{\circ}C$ in the proportion of 4 mW/°C.

Electrical Characteristics (Unless specified otherwise, V_{CC1} = 2.8 V, V_{CC2} = 1.2 V, R_g = 600 $\Omega,~R_L$ = 16 $\Omega,~f$ = 1 kHz, Ta = 25°C)

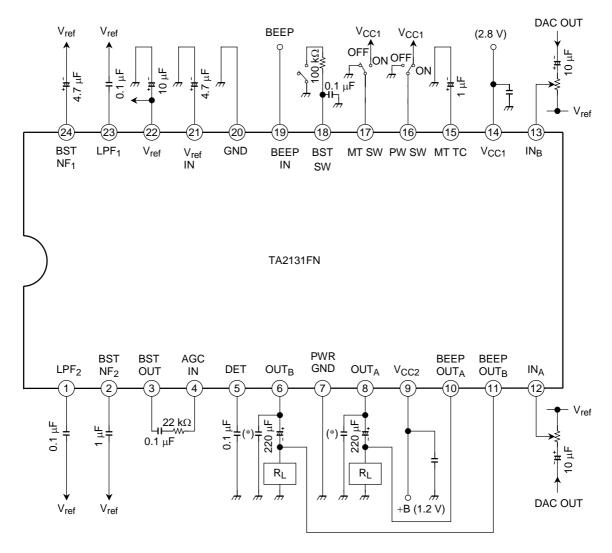
Characteristic		Symbol	Test condition	Min	Тур.	Max	Unit	
		I _{CC1}	IC OFF (V _{CC1}), SW1: b, SW2: b	_	0.1	5	μΑ	
		I _{CC2}	IC OFF (V _{CC2}), SW1: b, SW2: b	_	0.1	5	μΛ	
Ouid	escent supply current	I _{CC3}	MUTE ON (V _{CC1}), SW1: a, SW2: b	_	0.35	0.50	mA	
Quie	escent supply current	I _{CC4}	MUTE ON (V _{CC2}), SW1: a, SW2: b	_	5	10	μΑ	
		I _{CC5}	No signal (V _{CC1}), SW1: a, SW2: a	_	0.55	0.75	mA	
		I _{CC6}	No signal (V _{CC2}), SW1: a, SW2: a	_	0.20	0.40		
Pow	er supply current during	I _{CC7}	$P_0 = 0.5 \text{ mW} + 0.5 \text{ mW} \text{ output (V}_{CC1})$	_	0.6	_		
drive	9	I _{CC8}	$P_0 = 0.5 \text{ mW} + 0.5 \text{ mW} \text{ output (V}_{CC2})$	_	5.3	_		
	Gain	G _V	$V_0 = -22 dBV$	10	12	14	dB	
	Channel balance	СВ	$V_0 = -22 dBV$	-1.5	0	1.5	- ub	
	Output power	P _{omax}	THD = 10%	5	8	_	mW	
	Total harmonic distortion	THD	P ₀ = 1 mW	_	0.1	0.3	%	
tion	Output noise voltage	V _{no}	$R_g = 600 \Omega$, Filter: IHF-A, SW4: b	_	-102	-96	dBV	
Sect	Crosstalk	СТ	$V_0 = -22 dBV$	-42	-48	_		
Power Section	Si I i i i i	RR1	$f_r = 100 \text{ Hz}, V_r = -20 \text{dBV}$ inflow to V_{CC2}	-71	-77	_	d۵	
	Ripple rejection ratio	RR2	$f_r = 100 \text{ Hz}, V_r = -20 \text{dBV}$ inflow to V_{CC1}	-54	-64	_	dB	
	Mute attenuation	ATT	$V_0 = -12 dBV$, SW2: $a \rightarrow b$	-90	-100	_		
	Beep sound output voltage	VBEEP	V Beep IN = 2 V _{p-0} , SW2: b	-53	-48	-43	dBV	
		BST1	$V_0 = -20 dBV, f = 100 Hz,$ SW3: ON \rightarrow OPEN	1	4	7		
Воо	st gain	BST2	$V_0 = -30 dBV$, $f = 100 Hz$, SW3: ON \rightarrow OPEN	10	13	16	dB	
		BST3	$V_0 = -50 dBV$, $f = 100 Hz$, SW3: ON \rightarrow OPEN	13.5	16.5	19.5		

Test Circuit



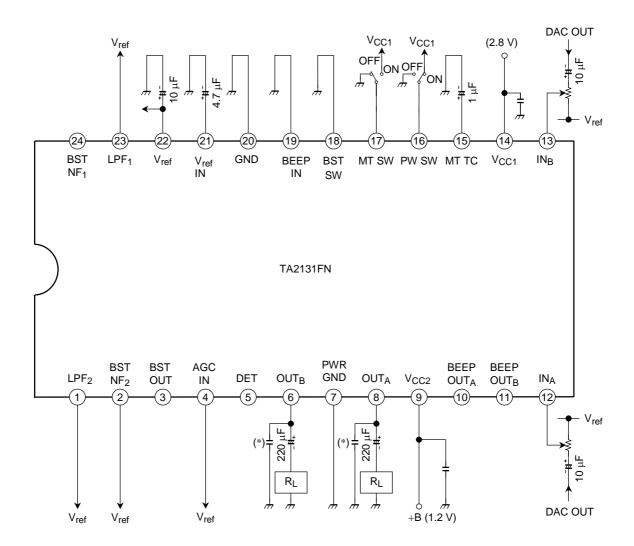
(*) 0.22 μF + 10 Ω Monolithic ceramic capacitor

Application Circuit 1



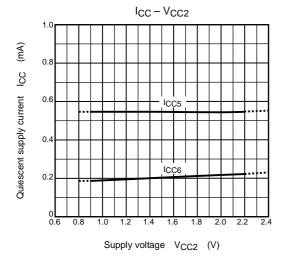
(*) 0.22 μF + 10 Ω Monolithic ceramic capacitor

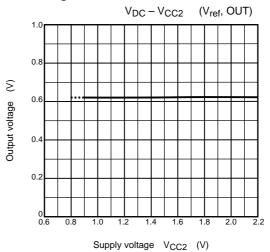
Application Circuit 2 (Low-Pass Compensation/Bass Boost Function/Beep Not Used)

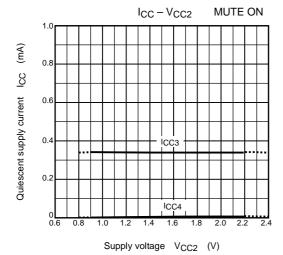


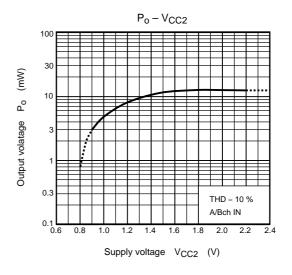
(*) $0.22~\mu\text{F} + 10~\Omega$ Monolithic ceramic capacitor

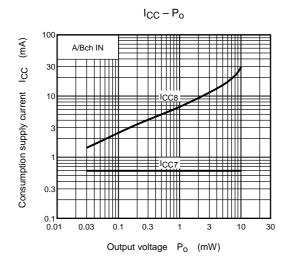
Characteristics (Unless otherwise specified $V_{CC1}=2.8$ V, $V_{CC2}=1.2$ V, $R_g=600$ Ω , f=1 kHz, Ta=25°C)

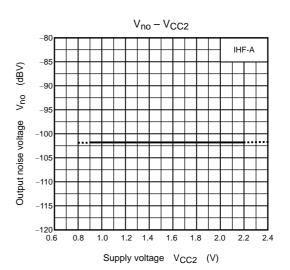


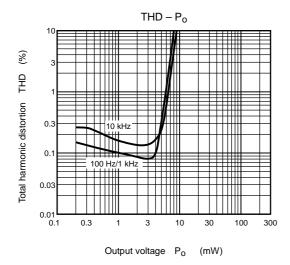


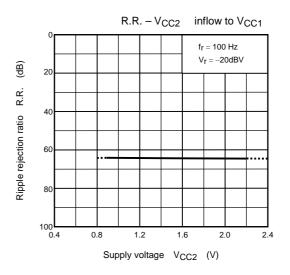


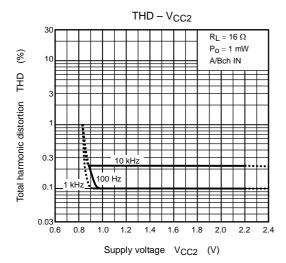


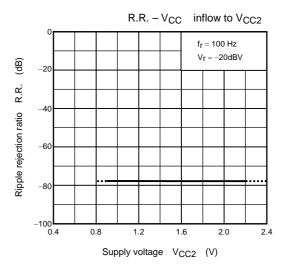


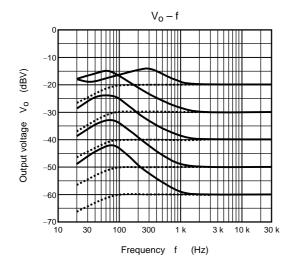


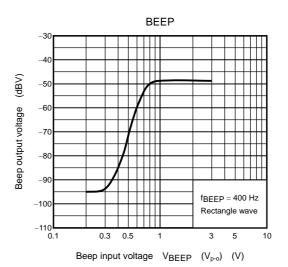


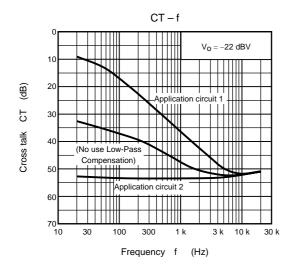


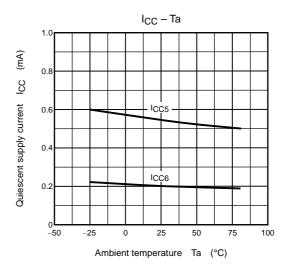


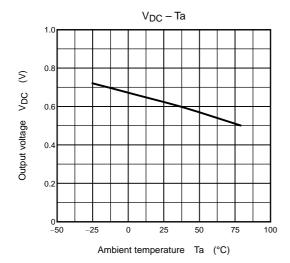




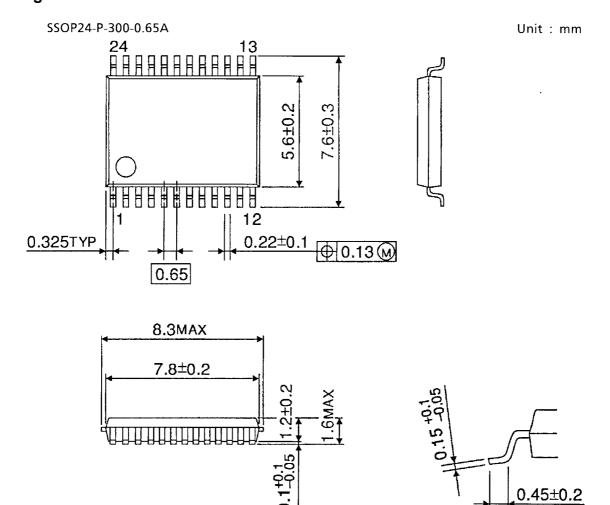








Package Dimensions



Weight: 0.14 g (typ.)

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